What is claimed is:

1. A package for accommodating electronic parts, comprising:

a structure, wherein a buildup substrate having a power source and/or a ground layer formed on a core substrate, and signal lines formed on a buildup interconnecting layer is adhered to a stiffener with a conductive adhesive layer using a conductive adhesive, and a grounding plane is formed using said stiffener and said buildup substrate.

2. The package for accommodating electronic parts according to claim 1, wherein said package is constituted so as to fix said conductive adhesive layer at a grounding potential.

3. The package for accommodating electronic parts according to claim 2, further comprising a plurality of ground connecting pads, said pads being provided on said buildup interconnecting layer, and said conductive adhesive layer having mainly a conductive adhesive.

4. The package for accommodating electronic parts according to claim 1, further comprising pads connected to said grounding plane, said pads being provided on the surface of said buildup substrate and being electrically connected to said conductive adhesive layer.

5. The package for accommodating electronic parts according to claim 4, further comprising a plurality of ground connecting pads, said pads being provided on said buildup interconnecting layer, and said conductive adhesive layer having mainly a conductive adhesive.

6. The package for accommodating electronic parts according to claim 1, further comprising a plurality of ground connecting pads, said pads being provided on said buildup interconnecting layer, and said conductive adhesive layer having mainly a conductive adhesive.

7. A semiconductor device, comprising:

a grid-array structure, wherein a buildup substrate having a power source and/or a ground layer formed on a core substrate, and signal lines formed on a buildup interconnecting layer is adhered to a stiffener with a conductive adhesive layer using a conductive adhesive, and a grounding plane is formed using said stiffener and said buildup substrate, after a semiconductor chip has been installed on said buildup substrate through a bump, the vicinity of the bottom of said semiconductor chip is fixed on the central portion of said buildup substrate with under-fill resin, said semiconductor chip is sealed with said stiffener and said conductive adhesive layer, and a solder ball is fixed to said bump.

8. The semiconductor device according to claim 7, wherein said semiconductor device is so constituted as to fix said conductive adhesive layer in said ball grid array structure at a grounding potential.

9. The semiconductor device according to claim 8, further comprising a plurality of ground connecting pads being provided on said buildup interconnecting layer in said ball grid array structure, and said conductive adhesive layer having mainly a conductive adhesive is connected to said plurality of ground connecting pads.

10. The semiconductor device according to claim 7, further comprising pads connected to said grounding plane in said ball grid array structure, said pads being provided on the surface of said buildup substrate and being electrically connected to said conductive adhesive layer.

11. The semiconductor device according to claim 10, further comprising a plurality of ground connecting pads being provided on said buildup interconnecting layer in said ball grid array structure, and said conductive

adhesive layer having mainly a conductive adhesive is connected to said plurality of ground connecting pads.

12. The semiconductor device according to claim 7, further comprising a plurality of ground connecting pads being provided on said buildup interconnecting layer in said ball grid array structure, and said conductive adhesive layer having mainly a conductive adhesive is connected to said plurality of ground connecting pads.

13. A method for manufacturing a package for accommodating electronic parts, comprising the steps of:

adhering a buildup substrate having a power source and/or a ground layer formed on a core substrate, and signal lines formed on a buildup interconnecting layer to a stiffener with a conductive adhesive layer using a conductive adhesive; and

forming a grounding plane using said stiffener and said buildup substrate.

14. The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the step of fixing said conductive adhesive layer at a grounding potential.

15. The method for manufacturing a package for accommodating electronic parts according to claim 14, further comprising the steps of :

providing a plurality of ground connecting pads on said buildup interconnecting layer; and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.

16. The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the step of providing

pads connected to said grounding plane on the surface of said buildup substrate as well as electrically connecting said pads to said conductive adhesive layer.

17. The method for manufacturing a package for accom modating electronic parts according to claim 16, further comprising the steps of :

providing a plurality of ground connecting pads on said buildup interconnecting layer; and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.

18. The method for manufacturing a package for accommodating electronic parts according to claim 13, further comprising the steps of :

providing a plurality of ground connecting pads on said buildup interconnecting layer; and

connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads.